


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/23/13840	
1.3 Title of PCN	ASE KaoHsiung (Taiwan) LQFP 24x24 package copper palladium bonding wire introduction on STM32F2/F4/F7x and STM32H5/H7x listed products	
1.4 Product Category	STM32F2x, STM32F4x, STM32F7x, STM32H5x, STM32H7x	
1.5 Issue date	2023-02-15	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ASE Kaohsiung (TAIWAN)

4. Description of change

	Old	New
4.1 Description	<p>Current Wire bonding material:</p> <ul style="list-style-type: none"> - ASE KaoHsiung (Taiwan) gold wire <p>Current Glue material:</p> <ul style="list-style-type: none"> - Sumitomo CRM 1076WA - YIZTECH 8143 	<p>New Wire bonding material :</p> <ul style="list-style-type: none"> - ASE KaoHsiung (Taiwan) copper palladium wire <p>Glue Material :</p> <ul style="list-style-type: none"> - Sumitomo CRM 1076WA - YIZTECH 8143 Additional Glue material : - HITACHI EN4900G
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
-----------------	---

7. Timing / schedule

7.1 Date of qualification results	2023-01-27
7.2 Intended start of delivery	2023-03-21
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13840 MDG-GPM-RER2303-V1.0-PCN13840-ASEKH LQ24x24 Low cost wire introduction.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-02-15

9. Attachments (additional documentations)
13840 Public product.pdf 13840 MDG-GPM-RER2303-V1.0-PCN13840-ASEKH LQ24x24 Low cost wire introduction.pdf 13840 PCN13840_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F765IGT6	
	STM32F767IGT6	
	STM32F777IIT6	
	STM32F779IIT6	
	STM32F407IGT6	
	STM32F427IGT6	
	STM32F479IIT6	
	STM32F765IIT7	
	STM32F767IIT6	
	STM32F769IGT6	
	STM32F769IIT6	
	STM32H745IIT6	
	STM32H747IGT6	
	STM32H747IIT6	
2850999	STM32H753IIT6	
3515804	STM32H757IIT6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved